



## Product Change Notification / MFOL-12SBEE528

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**Date:**

28-Oct-2022

**Product Category:**

PON ONU/OLT Devices, SAS Silicon & SW, SONET/SDH/T1/E1 Devices

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 5284 Final Notice: Qualification of GX92 as a new substrate material for PM8005C-F3EI, PM8004C-F3EI, XYRPM8005C-F3EI, XYRPM8004C-F3EI, PAS5211A-F3EI, and PM5369-FEI catalog part numbers (CPN) available in 592L BGA (27x27x2.24mm), 896L BGA (31x31x2.24mm), and 672L BBGA (27x27x3.32mm) packages assembled at STAK assembly site.

**Affected CPNs:**

[MFOL-12SBEE528\\_Affected\\_CPN\\_10282022.pdf](#)

[MFOL-12SBEE528\\_Affected\\_CPN\\_10282022.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of GX92 as a new substrate material for PM8005C-F3EI, PM8004C-F3EI, XYRPM8005C-F3EI, XYRPM8004C-F3EI, PAS5211A-F3EI, and PM5369-FEI catalog part numbers (CPN) available in 592L BGA (27x27x2.24mm), 896L BGA (31x31x2.24mm), and 672L BBGA (27x27x3.32mm) packages assembled at STAK assembly site.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	STATS CHIPPAC KOREA LTD. (STAK)	STATS CHIPPAC KOREA LTD. (STAK)
Die Attach Material	WF6317	WF6317
Underfill material	U8410-73C	U8410-73C
Solder Ball	SAC305	SAC305
Substrate Material	GX3	GX92

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying GX92 as a new substrate material.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**November 20, 2022 (date code: 2248)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	October 2022					November 2022			
	41	42	43	44	45	46	47	48	49
Qual Report Availability				X					
Final PCN Issue Date				X					
Estimated Implementation Date								X	

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**October 28, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_MFOL-12SBEE528\\_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

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